Time Stamp	2004/09/22 10:37	2004/09/22 10:37	2004/09/22 10:38	2004/09/22 10:38	2004/09/22 10:38	2004/09/22 10:39	2004/09/22 10:39	2004/09/22 13:04	2004/09/22 13:15
Plurals	OFF	0FF	OFF						
Default Operator	OR.	æ	R	R	R	S.	80	8	No.
DBs	US-PGPUB; USPAT; EPO; JPO; DERWENT								
Search Query	451/56.ccls.	451/60.cds.	polish\$3	451/41.cds. and polish\$3	451/56.cds. and polish\$3	451/60.cds. and polish\$3	ped	"3-hydroxy-4-pyranes"	("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or borner bordyrdrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogulinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)
Hits	704	478	254722	2208	480	380	419839	4	106256
Ref #	S1 ·	23	ß	\$	S	%	2S	8	S3

EAST Search History

210	955901	("3-hvdroxv-4-rvmnes") or	IIS-PGPUB.	ã	O. T.	7004/09/22 13:17
		(hydroxy adj) butyroladones) or borane or borohydrides or (dialkylamine adj boranes) or formaldelyde or (formic adj acid) or hydrogen or hydroquirones or hydroxylamine or (hypophosphorous adj acid) or trihydroxybentzene or (solvated adj electrons) or (sulfurous adj acid)	USPAT; EPO; JPO; DERWENT	j	;	
S11	303143	("428" or "156" or "51").das.	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:18
S12	43264	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogan hydroquinones hydroxylamine (hypophosphorous adj acid) thihydroxylamine (sopverzene (sobvated adj electrons) (sulfurous adj acid) 1 and (("428" or "156" or "51").clas.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĸ	FIO.	2004/09/22 13:18
S13	0	"451.das"	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:18
514	64433	"451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	& S	OFF	2004/09/22 13:18
515	1097	(("3-hydroxy-4-pyrones") or (hydroxy adj. butyrolactones) or borane boronydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) thiydroxylenzene (sohvated adj electrons) (sulfurous adj acid)) and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ő	OFF	2004/09/22 13:19
S16	2868440	reducing agent	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:23

7/5/07 10:17:13 AM C:\[Cournents\] C:\[Cournents\] COUNTENTS and Settings\[Cournerts\] Documents\[CAST\] Workspaces\[CAST\] Workspaces\[CAST\] Warb C:\[CAST\] Countents\[CAST\] Countents\[CAST\] Workspaces\[CAST\] Countents\[CAST\] Countents\[CAS

3		
į		
1		
:		
5		
_		
į		
֡		
,		
•		
ł		
ì		
•		

R

క

834

S17

US-PGPUB; USPAT; EPO; JPO; DERWENT

EAST Search History

2004/09/22 13:35	2005/01/24 13:20	2004/09/22 13:38
OFF	OFF 200	OFF 200
ő	ĸ	Ř
US-PGPUB; USPAT; EPO; JPO; DERWENT;	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-hydroxy 4-pyrones") or ((("3-hydroxy 4d) tutyrobactunes) or borane borohydrides (dialykamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) thydrogen hydroquinones opolish§3) and pad) or ((451/60.cds. and polish§3) and pad) or ((451/60.cds. and polish§3) and pad)) not (((451/41.cds. and polish§3) and pad)) not (((451/41.cds. and polish§3) and pad)) not ((13-hydroxy 4-pyrones") or (hydroxy adj) tutyroblactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydroxylemine (hypophosphorous adj acid) hydroxylemine (hybophosphorous adj acid) hydroxylemine (hybophosphorous adj acid) and ((451/41.cds. and polish§3) and pad) or ((451/60.cds. and polish§3) and pad))))	((451/41.cds. and polish\$3) and pad) and (("3-hydroxy-4-pyrones") or (hydroxy ad) burynaletones) or borane borohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid) and (((451/41.cds. and polish\$3) and pad) or ((451/60.cds. and polish\$3) and pad))))	("3-hydroxy-4-pyranes") or (hydroxy adj. bukyralextones) or borane borohydrides (dialydamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophoxphoxphoroxed) acid) trihydroxyberzene (solvated adj electrone) (sulfurous adj acid) and ((1451,55c.ds. and adj. adj. adj. ((1451,55c.ds. and adj. adj. adj. adj. adj. adj. adj. adj
64	288	93
	ξξ,	524

2004/09/22 13:23	2004/09/22 13:34	2004/09/22 13:31	2004/09/22 13:31	2004/09/22 13:42	

Ħ

8

(451/56.ccls. and polish\$3) and pad

396

S19

US-PGPUB; USPAT; EPO; JPO; DERWENT

片

8

(451/60.ccls. and polish\$3) and pad

263

220

US-PGPUB; USPAT; EPO; JPO; DERWENT

P.

ర

337

27

US-PGPUB; USPAT; EPO; JPO; DERWENT

("3-hydroxy-4-pyrones") or (hydroxy adi) butyrolactones) or borane borothydrides (dialkylamine adj boranes) formaldelayde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)) and (((451/41.cds, and polish\$3) and pad) or ((451/60.cds, and polish\$3) and pad) or ((451/60.cds, and polish\$3) and pad))

R

8

(451/41.cds. and polish\$3) and pad

1562

S18

US-PGPUB; USPAT; EPO; JPO; DERWENT

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

2006/02/14 15:39	2004/09/22 14:22	2004/09/22 14:18	2004/09/22 14:19	2004/09/22 14:22	2004/09/22 14:23	2004/09/22 14:23	2005/01/21 15:29	2005/01/21 15:11	2005/01/21 15:12
OFF	FF0	FF0	OFF	JE OFF	OFF	OFF		PF0	OFF
OR	క	8	OR	8	æ	8	8	8	80
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	USPAT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(("3-hydroxy 4-pyrones") or (hydroxy adj.1 butyrolactones) or borane borolydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybenzene (sokrated adj electrons) (sulfurous adj acid) 1 and ((451/41.cds. and polish\$3) and pad)	oxidize\$4 and abrasive and polish\$4	oxidize\$2 and abrasive and polish\$4 and (reducing adj agent) and ((liquid or aqueous) adj carrier)	("4769046" "5489233" "6001269" "5527423" "5958794" "6001269" "61157000" "6117000" "6117000" "6117000" "6117000" "6117000" "6117000" "6117000" "2002/0004360" "2002/0010232" "2002/0017630").PN.	tantalum	451/41.cds.	tantalum and 451/41.ccls.	(\$1-alumina or alpha-alumina or (alpha near alumina)) with abrasive	"451.clas"	"451".clas.
288	3038		12	77604	2905	190	895	0	64929
	S26	223	258		 83	 IS	233	83	S34

7/5/07 10:17:13 AM C:\Documents\EAST\Workspaces\10753138.wsp

EAST Search History

2005/01/21 16:01	2005/01/21 15:30	2005/01/21 15:30	2005/01/21 15:31	2005/01/21 16:01	2005/01/21 16:01	2005/01/21 16:01	2005/01/24 09:38	2005/01/24 10:45	2005/01/24 10:48	2005/01/24 09:58
FF0	OFF	OFF	OFF	FFO	FFO	J-FO		FFO	F10	OFF.
8	R	R	8	8	R	8	R	8	R R	g
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
S32 and S34	(silica or (fumed adj alumina)) with abrasive	(S32 or S36) and S34	S35 and (reducing adj agent)	S37 and (reducing adj agent)	S36 and S34	S40 and (reducing adj agent)	"6454822".pn.	"451".das.	S43 and ((indium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad or abrasive))	S43 and ((iridium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad) or abrasive)
8	6947	. 1138	II	27	1109	24	2	64929	195	195
SSS	336	23,	838	g	8	<u>*</u>	845	8	*	25

7/5/07 10:17:13 AM C:\Documents\EAST\Workspaces\10753138.wsp

Page 5

2005/01/24 09:59	2005/01/24 10:08	2005/01/24 11:17	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:16	2005/01/24 10:16
OFF	OFF		OFF		OFF	OFF		
g	S S	æ	OR	OR.	SO.	SO.	S.	OR S
US-PGPUB; USPAT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; •USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT				
(US-20020182982-\$ or US-20030013387-\$ or US-20040013385-\$ or US-20040132385-\$).did. or (US-649822-\$ or US-6709316-\$). did.	S45 and S46	(silicone adj oxide) with "Si"	silicone near4 metal	silicone near2 metal	silicone near1 metal	S43 and S51	S43 and S50	S43 and S49
9	2	37	6851	2852	740	-	2	1
25	**	84.		055	221		SS	\$ 5

SSS	01	SS4 not SS1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	æ	PF.	2005/01/24 10:17
S26	v	S54 not S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	&	PF0	2005/01/24 10:23
	0	S47 and (indium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S S	OFF	2005/01/24 10:24
828	2	S43 and (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S S	OFF	2005/01/24 10:47
829	212721	"428".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	R	OFF	2005/01/24 10:46
98	609	(substrate or wafer or semiconductor or semi-conductor) with (indium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	SO.	- PF	2005/01/24 10:49
55	2	S43 and (iridium adj oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S.	OFF	2005/01/24 10:49
298	15	((substrate or wafer or semiconductor or semi-conductor) with (indium adj oxide)) and ((polishing adj pad) or abrasive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	SO.	OFF	2005/01/24 10:50
98	1388	(copper adj oxide) with "Cu"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	g ,	OFF	2005/01/24 11:17
\$	ω	S63 and S43	USPAT; USPAT; USOCR; EPO; JPO; DERWENT	S.	PPO	2005/01/24 11:17

7/5/07 10:17:13 AM Cettings/bmuller/My Documents/EAST\Workspaces\10753138.wsp

Page 8

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

2005/01/24 13:23	2005/01/24 13:23	2005/01/24 13:24	2005/01/24 13:24	2005/01/24 14:09	2005/01/24 14:09	2005/01/24 14:11	2005/07/12 10:33	2005/07/12 10:33	2005/07/12 10:33	2005/07/12 10:43
FF0	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	FF0
æ	8	g	8	8	S S	SO.	S S	8	۵ 8	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(indium adj oxide) and (polish polishing CMP ("chemical mechanical polishing"))	S65 and (reducing adj agent)	(indium adj oxide) and (CMP ("chemical mechanical polishing"))	(indium adj oxide) and (CMP or ("chemical mechanical polishing"))	(indium adj oxide) same (CMP or ("chemical mechanical polishing"))	"4717581".pn.	"4679572",pn.	451/41.cds. and polish\$3	451/56.cds. and polish\$3	451/60.cds. and polish\$3	(S72 S73 S74) and ("pH" near2 (buffering buffer buffer\$4))
999	4	569	695	2	2	2567	. 550	427	8
S65	3 8	267	88	698	S70	571	272	573	S74	575

EAST Search History

OFF 2005/07/12 10:55	OFF 2005/07/12 10:43	OFF 2005/07/12 10:44	OFF 2005/07/12 10:44	OFF 2005/07/12 10:56	OFF 2005/07/12 11:00	OFF 2005/07/12 11:05	OFF 2005/07/12 11:05
R	g	Ř	R	ଞ	뚕	೪	g
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR;
(S72 S73 S74) and (surfactant)	(ammonium adj hydroxide) same ("pt" near2 (buffering buffer buffer\$4))	(ammonium adj hydroxide) with ("pl" near2 (buffering buffer buffer\$4))	(ammonium adj hydroxide) near4 ("ph" near2 (buffering buffer buffer\$4))	(\$72 \$73 \$74) and ((advantages advantageous advantageous advantag\$5) with surfactant)	("451".clas.) and ((advantages advantageous advantag\$\$) with surfactant)	("451".clas.) and ((desired improve improved improvement) with surfactant)	"5783489".pn.
566	1183	366	105	7	v	4	7
S76	LLS	8278	S73	88	15 8	285	88

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

Page 9

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

2006/02/14 16:29

Ŗ

ర

US-PGPUB; USPAT;

DERWENT

polishing" or "chemical mechanical

(polishing adj (pad pads)) and (CMP or "chemical mechanical

82

planarization") and ((reducing adj agent) with (hydroxylamine and

("3-hydroxy-4-pyrones") or

(hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj

electrons) or (sulfurous adj acid)))

(polishing ad) (bad pads)) and

88

(CMP or "chemical mechanical

polishing" or "chemical mechanical

planarization") and ((reducing adj

agent) with (hydroxylamine with

(("3-hydroxy-4-pyrones") or

or hydrogen or hydroquinone\$3 or

(hydroxy adj.1 bukrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)

trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

((reducing adj agent) with

241

88

or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or

(hydroxylamine with (("3-hydroxy 4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or

(dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

(polishing adj (pad pads)) and

884

2006/02/14 15:44

2006/02/14 15:45

2006/02/14 15:45

7/5/07 10:17:13 AM C:\Documents and Settings\tbmuller\My Documents\EAST\Workspaces\10753138.wsp

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

or hydrogen or hydroquinone\$3 or

formaldehyde or (formic adj acid)

(dialkylamine adj borane\$3) or

borane or borohydrides or

(hydroxy adj1 butyrolactones) or

(("3-hydroxy-4-pyrones") ar

((reducing adj agent) with (hydroxylamine with

**	ιν .	(CMP or "dremical mechanical polishing" or "dremical mechanical planarization") and ((reducing adjagent) with (hydroxylamine and (('3-hydroxy-4-pyrones') or (hydroxy adj1 butyrolectones) or (hydroxy adj1 butyrolectones) or or hydroxylamine adj boranes3) or formaldehyde or (formic adjado) or hydrogen or hydroquimone\$3 or fytyophosphorous adjado) or hydrogen or hydroquimone\$3 or hydroxybenzene or (sohvated adjelectons) or (sulfurous adjacid))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	x	OFF	2006/02/14 16:56
8		(semiconductor wafer polish planarize substrate copper) and ((reducing adj agent) with ((reducing adj agent) with (hydroxylamine and ((''3-hydroxy-4-pyrones'') or (hydroxy adj! butyrolactones) or channer or browhydrides or (dialkylamine adj boranes) and porane or browhydrides or (dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones) ar (hypophosphorous adj acid) or hydrogen or hydroquinones) or trihydroxybenzæne or (solvated adj electrons) or (sulfurous adj acid))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĸ	OFF	2006/02/14 15:49
85	176	(wafer polish planarize substrate copper) and ((reducting adi agent) with (hydroxylamine aind (("3-hydroxyl-pyrones") or (hydroxyl-pyrones") or (hydroxyl-pyrones) or (hydroxylamine adi buranes) or formatolehyde or (formic adi acid) or formatolehyde or (formic adi acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adi acid) or hydrogen or hydroquinone\$3 or thihydroxybenzene or (solvated adi electrons) or (sulfurous adi acid))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	Ř	FIO	2006/02/14 15:49
83		(semiconductor polish planarize substrate copper) and ((reducing adj agent) with ((hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolectones) or borane or brohydrides or (dialkylamine adj boranes)) or formaldehyde or ((ormic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorus adj acid) or hydrogenous adj acid) or hydrogenous adj acid) or hydrogenous adj acid) or trihydroxybenzene or (sohated adj electrons) or (suffinous adj acid)))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĸ	FO	2006/02/14 15:49

7/5/07 10:17:13 AM C:Uocuments and Settings/brnuller/My Documents/EAST\Workspaces\10753138.wsp

2006/02/14 15:49	2006/02/14 15:56	2006/02/14 15:50	2006/02/14 15:50
940	F	PF.	OFF
క	ĸ	ХO	Ř
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(semiconductor planarize substrate opper) and ((reducing adi agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or hydroxy adi! butyrolactones) or borane or borohydrides or (hydroxy adi! butyrolactones) or borane or borohydrides or (lalkylamine adi boranes3) or formaldehyde or (formic adi acid) or hydrogen or hydroquinones3 or (hypophosphoruse adi acid) or hydroquinones3 or hybophosphorusene or (solvated adi electrons) or (sulfurous adi acid))))	(semiconductor substrate copper) and (reducing adj agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or (hydroxy adj! butyrolactones) or corner or borohydrides or (dialkylamine adj borane\$}) or formaldebyde or (formic adj acid) or formaldebyde or (formic adj acid) or hydrogen or hydroquinone\$} 3 or flytpophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	((reducing adj agent) with ((reducing adj agent) with (hydroxylamine and ((1%3-hydroxy4-pyrones*) or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquintone\$3 or (hypophosphorous adj acid) or hydrogen or hydroquintone\$3 or hydrogen or hydroquintone\$3 or hydrogen or hydroquintone\$3 or thihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	(semiconductor substrate) and (reducing adj agent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or borane or borohydrides or (daikylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorus adj acid) or hydrogenous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfinous adj acid))
185	185	153	
283	88	88	293

EAST Search History

Ξ	9899	=	5	φ
2006/02/14 16:11		2006/02/14 16:11	2006/02/14 16:51	2006/02/14 16:46
720/90		720/90	720/90	720/07/
8		500	20	20
OFF		PH0	T	PFO
g		g	8	8
US-PGPUB;	EPO, JPO, DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
US-PGP		US-PGP USPAT; EPO; JPC DERWEN	US-PGPAT, USPAT, EPO; JR EPO; JR DERWEN	US-PGPU USPAT; EPO; JPV DERWEI
(semiconductor semiconductors)	(hydroxylamine and ("3-hydroxylamine and ("3-hydroxylamine and hydroxy adjl butynoladones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	("451".cdas.) or ("428".cdas.) or ("51".cdas.)) and ((reducing adjagent) with (hydroxylamine and ("3-hydroxy-4-pyrones") or (hydroxy adj. bu/hyrolactones) or borane or borohydrides or completive or (formic adjacid) or hydrogen or hydroquinones) or (hypophosphorous adjacid) or trihydroxybenzene or (solvated adjelectrons) or (sulfurous adjacid))))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical plannical mechanical plannication") and ((reducing adjagent) with (("3-hydroxy-4-pyrones") or (hydroxy adji butynolactones) or borane or borohydrides or borane or borohydrides or dialkyamine adj borane\$3) or formaldehyde or (formic adj acid) or hydroxpenrous adj acid) or thihydroxybenzene or (sohvated adjelectrons) or (sulfurrous adj acid)))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization")) and (slurry composition solution) and (reducing adj agent) with ((reducing adj agent) with ((ra-hydroxy4-pyrones") or (hydroxy adj) butyrolactones) or borane or borohydrides or chydrogune adj borane\$3) or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogunone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))
53		=	345	308
965		283	865	665

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

7/5/07 10:17:13 AM C:Ubcuments and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

	OFF 2006/02/14 16:51	OFF 2006/02/14 16:51	OFF 2006/02/14 16:57
.	<u>g</u>	٥ 0	o o
	US-PGPUB; USPAT; EPQ; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
	((toolishing adi (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical phanarization") and (slurry composition) and ((reducing adi agent) with (("3-hydroxy-4-pyrones") or (hydroxy-4-pyrones") or borane or borohydrides or borane or borohydrides or formaldehyde or (formic adj acid) or hydrospen or hydroquinone\$3 or flypophosphorous adj acid) or hydrospen or silhydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))	((colishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical palnarization") and ((reducing adj agent) with (("3-hydroxy-4-pyrones") or (hydroxy adj butyrolactones) or borane or boranes adj acid) or formaldehyde or (formic adj acid) or hydroquinone\$\frac{1}{2}\$ or formaldehyde or (formic adj acid) or hydroquinone\$\frac{1}{2}\$ or fyrpophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization" and ((reducing adjagent) with ((reducing adjagent) with ((rydroxylamine adj iodide)) with (("3-hydroxy 4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (hydroxy adj1 butyrolactones) or borane or borohydrides or (idalkylamine adj borane\$\$\frac{1}{2}\$) or (dialkylamine adj borane\$\$\frac{1}{2}\$) or (dialkylamine adj acid) or hydrogen or hydrogulmone\$\$\frac{1}{2}\$\$ or byhydroxybenzene or (solvated adj
	223	214	4
	S10 0	\$10 1	510

EAST Search History

2006/02/14 17:17	2006/02/14 16:57	2006/02/14 17:01
FO.	F F	F O
ಕ	R	<u>R.</u>
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(CMP or "dremical mechanical polishing" or "dremical mechanical planarization") and ((reducing adjagent) with (hydroxydantine with (("3-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or borane or borchydrides or (hydroxy adj! butyrolactones) or borane or borchydrides or (falkydamine adj borane\$3) or (dialkydamine adj borane\$3) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adjelectrons) or (sulfurous adj acid))))	(CMP or "chemical mechanical polishing" or "chemical mechanical phararization" and (freducing adjagent) with (glucose sulfothionate (podassium adj iodidel) with (("3-hydroxy-4-pyrones") or (hydroxy adj! bubynolactones) or borane or borohydrides or (frume adj acid.) or formaldehyde or (formic adj acid.) or hydrogen or hydroquimone\$3 or formaldehyde or fydroquimone\$3 or fytpophosphorous adj acid.) or hydrogen or hydroquimone\$3 or thinydroxybenzene or (solvated adjectorns) or (sulfurous adj acid)))	((colishing adj (pad pads)) or planarize planarization slurry) and ((reducing adj agent) with ((clucose sulfothionate (potassium adj iodide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj 1 butyrolactones) or borane or borane or borane adj boranes) or formaldehyde or (formic adj acid) or hydroxpannines) or hydroxpuinones) or hydroxpen or hydroxpuinones) or hydroxyberizene or (solvated adj electrons) or (sulfurous adj acid)))
4	0	4
33	4 4	5 20

2006/02/14 17:01	2006/02/14 17:49	2006/02/14 17:48	2006/02/14 17:53
HO.	0FF	Ħ.	PF0
.	క	ర	& S
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((polishing adj (pad pads)) or planarize planarization) and ((reducing adj agent) with ((glucose sulfothionate (potassium adj iodide)) with (("3-hydroxy 4-pyranes") or (hydroxy adj butynolactones) or borane or borohydrides or (formic adj acid) or formaldehyde or (formic adj acid) or formaldehyde or (formic adj acid) or formaldehyde or (formic adj acid) or fydnogen or hydroquimone\$3 or (hypophosphorus adj acid) or thihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	(CMP or "dremical mechanical polishing" or "dremical mechanical planarization") and (hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj: hydrody adj: hydrody adj: hydroladiones) or borane or borohydrides or (dialkylamine adj borane\$3) or (dialkylamine adj borane\$3) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid)) or hydrogynous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))	(CMP or "chemical mechanical polishing" or "chemical mechanical phanarization" and (tytoxyalmine with (("2-hydroxy-4-pyrones") or (hydroxy adj! butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldebyde or (formic adj acid) or hydrogen or hydroquinone\$3 or thydroxphorous adj acid) or hydrogensene or (solvieted adj electrons) or (suffurous adj acid) or thydroxpensene or (solvieted adj electrons) or (suffurous adj acid) not (hydrogen adj peroxide)))	(CMP or "dremical mechanical polishing" or "dremical mechanical planarization") and (hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adi) butyrolactones) or borane or borohydrides or (dialkylamine adi borane\$3) or (dialkylamine adi peroxide) or hydrogunone\$3 or hydroquinone\$3 or hydroquinone
0	105	105	
9 9	7 7	8 8	810

EAST Search History

2006/02/14 17:49	2006/02/14 17:53	2006/02/15 08:55	2007/03/15 15:43	2006/02/15 09:28	2006/02/15 09:28	2007/03/15 12:06
OFF			OFF.	OFF	0FF	OFF
æ	د	S S	R	SA S	æ	8
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	us-Pgpub; Uspat; Usocr; Epo; Jpo; Derwent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
5107 not 5109	(CMP or "chemical mechanical polisting" or "chemical mechanical palaratratural archamical manaratratural archamical planaratratural archamical	(complexing adj agent) with (chelating adj agent)	10/753138.app.	("20020039839" "20020090820" "2 0020102923" "20020111027" "2003 0013387" "20030119319" "548923 " "5274231" "5691219" "595879" "6117783" "63139763" "6274063" "6 313039" "6315803" "6419554" "652	09/755717.app.	((polishing cmp "dremical mechanical polishing" "chemical mechanical planarization").it.) and ((reducing adj agent) same (osalic adj acid) same ((dimethylamine adj borane) hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenrous sacid" trihydroxybenroes#4))
24	. 31	339	п	. 32	-	7
S11 0	1 1	2	33	S11 4	S111 5	S11 6

Page 17

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

2007/03/16 13:16	2007/03/15 12:55	2007/03/15 12:54	2007/03/15 12:55	2007/03/15 13:14	2007/03/15 12:55	2007/03/15 13:16	2007/03/15 13:15	2007/03/15 13:16	2007/03/15 13:17
OFF	OFF	0 FF	OFF	0FF	OFF	OFF		OFF.	OFF
&	g	8	8	Ŗ	8	8	R	R	క
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	us-pgpub; uspat; epo; jpo; derwent	US-PGPUB; USPAT; EPO; JPO; DERWENT	us-pgpub; uspat; epo; jpo; derwent	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((reducing adj agent) same ((oxalic adj acid) formaldehyde (formic adj acid)) same ((dimethylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$4))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor (oxidize\$4 near3 metal) slumy)	((polishing adj (pad pads composition compositions)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor (oxidize\$4 near3 metal) slumy)	S122 and S124	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor slumy)	S122 and S126	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor)	(reducing adj agent) same ((oxalic adj acid) formaldehyde (formic adj acid))	S128 and S129	((polishing adj (pad pads)) or (CMP or "chemical mechanical or "chemical mechanical planarization") semiconductor). ti.
437	2060024	2060877	100	2050060	22	1776495	8249	466	926469
S12 2	3.	S12 4	S12 5	S12 6	S12 7	S12 8	S12 9	S13 0	513

7/5/07 10:17:13 AM C:things\bmuller\My Documents\EAST\Workspaces\10753138.wsp

Page 19

7/5/07 10:17:13 AM C:\Documents and Settings\bmuller\My Documents\EAST\Workspaces\10753138.wsp

2007/03/15 13:17

뜽

8

S131 and S129

28

S13

US-PGPUB; USPAT; EPO; JPO; DERWENT

2007/03/15 13:21

P.

8

US-PGPUB;

mechanical polishing" "chemical

(polishing cmp "chemical

S13

mechanical planarization") and

USOCR; EPO; JPO; DERWENT USPAT;

((reducing adj agent) same (oxalic adj acid) same ((dimethylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphoric acid"

7

S13 8

249916

S13

Page 22

65	82214	legical methodical	I IC. DCDI IR.	8	110	2007/03/15 15:05	_
6	F1778	(City Creminal medianical polishing" "chemical mechanical planarization")	USPAT; USOCR; EPO; JPO; DERWENT	5 .	5	co:c1 c1 /c0 / c0:2	
S14 0	7.1	S136 and S138	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2007/03/15 15:06	
S14 1	9	S136 and S139	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2007/03/15 15:06	
S14 2	79	S136 and tantalum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2007/03/16 08:40	
33	28	S142 and S141	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	80	HO.	2007/03/15 15:07	
4 4	5029	((reducing adj agent) reductant reduc\$4) and ((oxalic adj acid\$3) formalehyled (formic adj acid\$3)) same ((dimethylam\\$4 adj borane\\$4) hydroquinon\\$4 "hydroquinone sulfonic acid" (hypophosphorsue adj acid\\$5) (hydrophosphors\\$4 adj acid\\$4) trihydroxybenz\\$8\\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	K	OFF	2007/03/15 15:34	
5	14	S136 and tantalum and redox	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S.	TFO.	2007/03/15 15:43	
S14 6	195	((polishing cmp "dhemical mechanical polishing" "chemical mechanical planarization")) and ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3) same ((dimethylam\$4 adj borane\$4) hydroquinone "hydroquinone sulfonic acid" (hypophosphorus adj acid\$3) (hydrophosphor\$4 adj acid\$3) trihydroxybenze\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	% S	OFF	2007/03/15 16:08	

2007/03/15 16:05

뜽

క

US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT

mechanical planarization").ti.) and ((oxalic adj acid\$3) formaldehyde

mechanical polishing" "chemical

S13

2007/03/15 13:21

R

ğ

US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT

(polishing cmp "chemical mechanical polishing" "chemical mechanical planarization") and

m

S13

trihydroxybenze\$4))

((reducing adj agent) same (oxalic adj acid) same ((dimethylamine adj borane) hydroquinone

"hydroquinone sulfonic acid"
"hypophosphorus acid"
trihydroxybenze\$4)) ((polishing cmp "chemical 2007/03/15 15:34

Ŗ

g

US-PGPUB;

(reducing adj agent) and ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinon\$4

937

S13 6

sulfonic acid" (hypophosphorous adj

acid\$3) (hydrophosphor\$4 adj acid\$4) trihydroxybenze\$4)

(formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinone "hydroquinone

08:27	16:37	08:39	08:38	08:39
2007/03/16 08:27	2007/03/15 16:37	2007/03/16 08:39	2007/03/16 08:38	2007/03/16 08:39
	5002	2007	500.	2007
F	OFF	P .	OFF	胺
& S	8	о́ С	Š.	SO.
				••
US-PGPUB; USPAT; USOCK; EPO; JPO; DERWENT	us-pgpub; uspat; usock; epo; jpo; derwent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCK; EPO; JPO; DERWENT	us-pgpub; uspat; usock; epo; jpo; derwent
((polishing cmp "dremical mechanical planarization"), it.) and mechanical planarization"), it.) and ((reducing adj agent) same ((oxalic adj acid) formaldeliyde (formic adj acid)) same (DMAB (dimethylamine adj borane) hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$41))	((polishing cmp "chemical mechanical polishing" "chemical mechanical plananzation"). It.) and ((reducing adj. agent) same ((oxalic adj. acid.) formaldeliyde (formic adj. acid.)) same (DMAB))	((polishing cmp "dremical mechanical planarizaton"), it.) and (((reducing adj agent) reducant reducer) same ((oralic adj agent) reducer) same ((oralic adj acid)) same (DMAB (dimethylamine adj borane) hydroquinone sulfonic acid" "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$4))	((polishing cmp "dremical mechanical planarization"), it.) and mechanical planarization"), it.) and (((reducing adj agent) reductant reducer) and ((oxalic adj acid)) formaldehyde (formic adj acid)) and (DMAB (dimethylamine adj borane) hydroquinone "hydroquinone" sulfonic acid" "hypophosphorous acid" trihydroxybenze\$4))	("451" clas.) and (((reducing adjagent) reductant reducer) and ((oxalic adjacid) formaldehyde (formic adjacid)) and (DNAB (dimethydamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphosphorous acid" trihydroxybenze\$4))
φ	0	v	φ .	-
514	S14 8	9	S15 0	S15 1

EAST Search History

2007/03/16 09:32	2007/03/16 08:51	2007/03/16 08:56	2007/03/16 09:07	2007/03/16 09:07	2007/03/16 09:32	2007/03/16 13:32	2007/03/16 13:34
/03/16	/03/16	/03/16	/03/16	/03/16	/03/16	/03/16	/03/16
2007	2007	2007	2007	2002	2002	2007	2007,
PF0	OFF	PP.	PPO PF	OFF	OFF	OFF	OFF
							•
ж С	ස <u>්</u>	g	g S	ğ	8	ర	8
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	us-pgpub; uspat; usocr; epo; jpo; derwent
(reducing adj agent) and ((oxalic adj acids3) formaldehyde (formic adj acids3)) same ((dimethylam\$4 adj borane\$4) hydroquinon\$4 adj borane\$4) hydroquinon\$4 (hypophosphorous adj acid\$3) (hydrophosphor\$4 adj acid\$4) trihydroxybenze\$4)	S152 and (tantalum adj oxide)	S152 and (tantalum adj oxide) and (indium ruthenium platinum rhodium palladium silver osmium gold)	S152 and (tantalum adj oxide) and ((iridium ruthenium platinum rhodium palladium silver osmium gold) near2 oxide)	S152 and (tantalum adj oxide) and ((iridium) near2 oxide)	(donat\$4 near3 electron\$4) same ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinona sulfonic acid" (hypophosphorous adj acid\$3) (hydrophosphor\$4 adj acid\$3) trihydroxybenze\$4)	(reducing adj agent) same ((oxalic adj acid) same ((dimethylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$41)	((known common typical) near3 (reducing adj agent\$3)) same ((coxalic adj acid) same ((dimethylamine adj borane) hydroquinone sulfonic acid" "hypophosphorous acid" thlydroxyberze\$4))
937	13		ω	2	4	\$	4
S15 2	33	S15 4	S15 5	S15 6	S15 7	S15 8	9

7/5/07 10:17:13 AM C:\Documents and Settings\brauller\My Documents\EAST\Workspaces\10753138.wsp

2007/06/27 11:03	2007/06/27 11:04	2007/06/27 11:04	2007/06/27 11:04	2007/06/27 11:32	2007/06/27 11:27	2007/06/27 11:27	2007/06/27 11:34
OFF	OFF	OFF	OFF	OFF	J-10	OFF	OFF
8	R	S S	೪	8	8	R	æ
US-PGPUB; USPAT; DERWENT	US-PGPUB; USPAT; DERWENT	US-PGPUB; USPAT; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(US-20020086511-\$ or US-20020017063-\$ or US-200200175844-\$ or US-20020042208-\$ or US-20020182982-\$ or US-20020182985-\$ or US-20040029495-\$ or US-2004012338-\$ or US-2004012385-\$ or US-2004012385-\$ or US-2003013387-\$ or US-2005011953-\$ or US-2002011953-\$ or US-2002011953-\$ or US-2002011953-\$ or US-20020130465-\$ or US-20020130465-\$ or US-6454822-\$ or US-568744-\$ or US-6703316-\$ or US-63764-\$ or US-6703316-\$ or US-63763-\$ or US-6709316-\$ or US-63263-\$ or US-6709316-\$ or US-632630-\$).	"23" and acsorbic	S160 and acsorbic	((polishing cmp "chemical mechanical polishing," "chemical mechanical planarization"). (it.) and ((reducing adj agent) same (ascorbic))	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization").ti.) and (ascorbic)	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization").tt.) and ((ascorbic) same (formic formaldehyde))	09/384946.app.	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization").ti.) and ((ascorbic) same reducing)
В	23	0	7	107	50	H	32
915	S16 1	S16 2	33	S16 4	5 5	S16 6	516

EAST Search History

S16 8	ટર	S167 not S165	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2007/06/27 11:38
99	2	10/901420.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S.	OFF	2007/06/27 11:40
0 0 0	4	("20010048161" "20020017063" "20020039839" "20020056701" "2002009820" "20020081853" "20020106975" "20020103923" "2002011027" "20020115384" "2002011027" "20030113319" "20030121891" "20030133116" "20031021891" "20030133116" "20030121891" "20030139116" "20030121891" "20030139116" "20030123107" "20030139116" "20030123107" "20030139116" "20030123870" "20030139116" "20030123870" "643927 "6290736" "6680787 "613192" "6295194" "6419554" "6527622" "6395194" "6419554" "665339" "6641630"),PN. OR ("7161247").	US-PGPUB; USDAT; USOCR	Ķ ·	946 1	2007/06/27 11:41
S17 1	80	S170 and ascorbic	US-PGPUB; USPAT; USOCR	ĕ	OFF	2007/06/27 13:09
S17 2		(polish\$4 and metal and oxid\$4 and ascorbic and abrad\$4).clm.	US-PGPUB; USPAT; USOCR	Ж	OFF	2007/06/27 13:09

Page 25

7/5/07 10:17:13 AM C:\Documents and Settings\briuller\My Documents\EAST\Workspaces\10753138.wsp